



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: RAEDER Examiner: Nguyen, D.
Serial No.: 09/383,876 Group Art Unit: 3723
Filed: August 26, 1999 Docket No.: AMDA.316PA

Title: POLISHING UNIFORMITY VIA PAD CONDITIONING

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this communication is being deposited in the United States Postal Service, as first class mail, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on June 26, 2001.

By:

Jose W. Jimenez

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated May 9, 2001, please consider the following response in connection with the above application.

In the Drawings

Please replace Figure 2 with amended Figure 2 (attached).

Remarks

The Office Action dated May 9, 2001, indicated that the drawings were objected to for failing to comply with 37 CFR 1.84 and 1.83(a) and that claims 1-12 stand rejected under §112, first paragraph, as not being enabled by the specification. Favorable reconsideration of this application is requested in view of the following remarks. For the reasons set forth below, Applicant respectfully submits that the claimed invention is properly enabled by the specification and the application is now in condition for allowance.

Applicant has amended the Figure 2 to include the numerals 140a and 230 and have provided a replacement figure page with this response. With respect to the Rule 83 objection, Applicant submits that wafer carrier 130 of Figure 2 illustrates an example embodiment of means for positioning the wafer misaligned with respect to the polishing means. A closer review of

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Response

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